

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>MING-HSIEN TSAI</td> <td>09/12/2013</td> </tr> <tr> <td>HSIEH-HUNG HSIEH</td> <td>09/12/2013</td> </tr> <tr> <td>TZU-JIN YEH</td> <td>09/12/2013</td> </tr> <tr> <td>CHEWN-PU JOU</td> <td>09/12/2013</td> </tr> <tr> <td>SA-LLY LIU</td> <td>09/12/2013</td> </tr> <tr> <td>FU-LUNG HSUEH</td> <td>09/23/2013</td> </tr> </tbody> </table>		Name	Execution Date	MING-HSIEN TSAI	09/12/2013	HSIEH-HUNG HSIEH	09/12/2013	TZU-JIN YEH	09/12/2013	CHEWN-PU JOU	09/12/2013	SA-LLY LIU	09/12/2013	FU-LUNG HSUEH	09/23/2013
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SA-LLY LIU	09/12/2013														
FU-LUNG HSUEH	09/23/2013														
RECEIVING PARTY DATA															
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.														
Street Address:	NO. 8, L I-HSIN ROAD 6														
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City:	HSIN-CHU														
State/Country:	TAIWAN														
Postal Code:	300-77														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14035979</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14035979										
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Application Number:	14035979														
CORRESPONDENCE DATA															
Fax Number:	(215)689-4905														
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ATTORNEY DOCKET NUMBER:	2013.0792/1085.01294														

CH \$40.00 14035979

NAME OF SUBMITTER:	PABLO MELES
Signature:	/Pablo Meles/
Date:	11/04/2013
Total Attachments: 3 source=ExecutedAssign#page1.tif source=ExecutedAssign#page2.tif source=ExecutedAssign#page3.tif	

**ASSIGNMENT AND AGREEMENT**

For value received, we, **Ming Hsien TSAI, Hsieh-Hung HSIEH, Tzu-Jin YEH, Chewn-Pu JOU, Sa-Lly LIU, and Fu-Lung HSUEH**, hereby transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Hsinchu Science Park, Hsin-Chu 300-77, Taiwan, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **THREE DIMENSIONAL CIRCUIT INCLUDING SHIELDED INDUCTOR AND METHOD OF FORMING SAME**, described in non-provisional patent application, and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof, or claiming priority therefrom that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

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Dated: 09/12/2013

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Dated: 09/12/2013

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Inventor No. 3

Dated: Sep 12, 2013

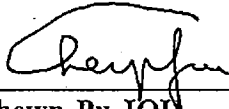
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Inventor No. 4

Dated: 2013, 09, 12

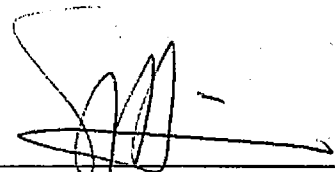
  
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Inventor No. 5

Dated: 2013. 9. 12

  
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Dated: 2013. 9. 23

  
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